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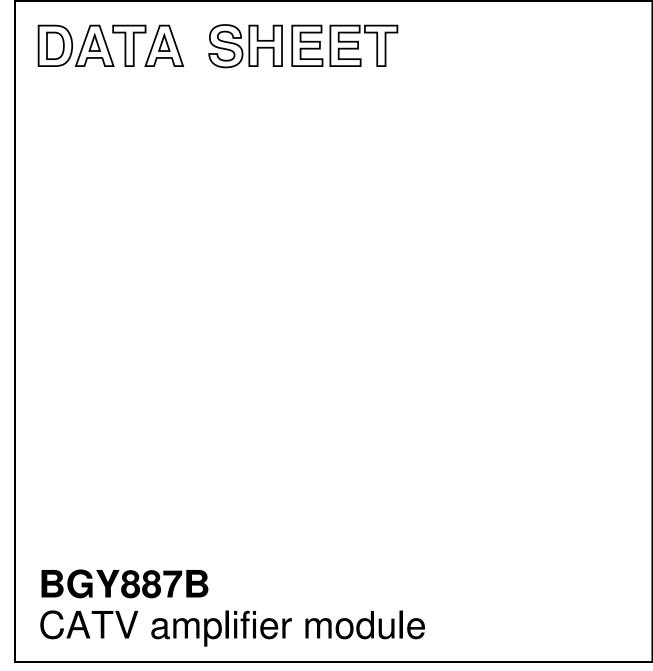


Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832 Email & Skype: info@chipsmall.com Web: www.chipsmall.com Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



DISCRETE SEMICONDUCTORS



Product specification Supersedes data of February 1995 1997 Apr 15



BGY887B

FEATURES

- Excellent linearity
- Extremely low noise
- High gain
- Excellent return loss properties.

APPLICATIONS

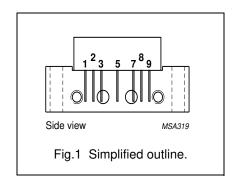
• Single-module line extender in CATV systems operating in the 40 to 860 MHz frequency range.

DESCRIPTION

Hybrid amplifier module in a SOT115J package operating with a voltage supply of 24 V (DC). This high gain module consists of two cascaded stages, both in cascode configuration.

PINNING - SOT115J

PIN	DESCRIPTION
1	input
2	common
3	common
5	+V _B
7	common
8	common
9	output



QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
G _p	power gain	f = 50 MHz	28.5	29.5	dB
		f = 860 MHz	29	-	dB
I _{tot}	total current consumption (DC)	V _B = 24 V	-	340	mA

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
Vi	RF input voltage	-	55	dBmV
T _{stg}	storage temperature	-40	+100	°C
T _{mb}	operating mounting base temperature	-20	+100	°C

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CHARACTERISTICS

Table 1 Bandwidth 40 to 860 MHz; $V_B = 24$ V; $T_{mb} = 30$ °C; $Z_S = Z_L = 75 \Omega$

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Gp	power gain	f = 50 MHz	28.5	29.5	dB
		f = 860 MHz	29	-	dB
SL	slope cable equivalent	f = 40 to 860 MHz	0.5	2.5	dB
FL	flatness of frequency response	f = 40 to 860 MHz	-	±0.5	dB
S ₁₁	input return losses	f = 40 to 80 MHz	20	_	dB
		f = 80 to 160 MHz	18.5	-	dB
		f = 160 to 320 MHz	17	-	dB
		f = 320 to 640 MHz	15.5	_	dB
		f = 640 to 860 MHz	14	-	dB
S ₂₂	output return losses	f = 40 to 80 MHz	20	-	dB
		f = 80 to 160 MHz	18.5	-	dB
		f = 160 to 320 MHz	17	-	dB
		f = 320 to 640 MHz	15.5	-	dB
		f = 640 to 860 MHz	14	-	dB
СТВ	composite triple beat	49 channels flat; $V_o = 44 \text{ dBmV}$; measured at 859.25 MHz	-	-60	dB
X _{mod}	cross modulation	49 channels flat; $V_o = 44 \text{ dBmV}$; measured at 55.25 MHz	-	-60	dB
CSO	composite second order distortion	49 channels flat; $V_o = 44 \text{ dBmV}$; measured at 860.5 MHz	_	-60	dB
d ₂	second order distortion	note 1	—	-70	dB
Vo	output voltage	d _{im} = -60 dB; note 2	58.5	-	dBmV
F	noise figure	f = 50 MHz	—	5	dB
		f = 550 MHz	—	5.5	dB
		f = 600 MHz	-	5.5	dB
		f = 650 MHz	_	5.5	dB
		f = 750 MHz	-	6	dB
		f = 860 MHz	-	6.5	dB
I _{tot}	total current consumption (DC)	note 3	-	340	mA

- 1. $f_p = 55.25 \text{ MHz}; V_p = 44 \text{ dBmV}; f_q = 805.25 \text{ MHz}; V_q = 44 \text{ dBmV};$ measured at $f_p + f_q = 860.5$ MHz.
- 2. Measured according to DIN45004B:
 - $f_p = 851.25 \text{ MHz}; V_p = V_o;$

 - measured at f_{p} + f_{q} f_{r} = 849.25 MHz.
- 3. The module normally operates at V_B = 24 V, but is able to withstand supply transients up to 30 V.

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SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
G _p	power gain	f = 50 MHz	28.5	29.5	dB
		f = 860 MHz	29	-	dB
SL	slope cable equivalent	f = 40 to 860 MHz	0.5	2.5	dB
FL	flatness of frequency response	f = 40 to 860 MHz	-	±0.5	dB
S ₁₁	input return losses	f = 40 to 80 MHz	20	-	dB
		f = 80 to 160 MHz	18.5	-	dB
		f = 160 to 320 MHz	17	-	dB
		f = 320 to 640 MHz	15.5	-	dB
		f = 640 to 860 MHz	14	-	dB
S ₂₂	output return losses	f = 40 to 80 MHz	20	-	dB
		f = 80 to 160 MHz	18.5	_	dB
		f = 160 to 320 MHz	17	_	dB
		f = 320 to 640 MHz	15.5	-	dB
		f = 640 to 860 MHz	14	-	dB
СТВ	composite triple beat	129 channels flat; V _o = 44 dBmV; measured at 859.25 MHz	_	-46	dB
X _{mod}	cross modulation	129 channels flat; V _o = 44 dBmV; measured at 55.25 MHz	-	-52	dB
CSO	composite second order distortion	129 channels flat; V _o = 44 dBmV; measured at 860.5 MHz	-	-53	dB
d ₂	second order distortion	note 1	-	-70	dB
Vo	output voltage	d _{im} = -60 dB; note 2	58.5	-	dBmV
F	noise figure	see Table 1	_	-	dB
I _{tot}	total current consumption (DC)	note 3	_	340	mA

Table 2	Bandwidth -	40 to 860 N	ИHz; V _B =	24 V; T _{mb} =	30 °C; Z _S =	= Z _L = 75	<u>δ</u>
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- $\begin{array}{ll} \mbox{1.} & \mbox{f}_p = 55.25 \mbox{ MHz}; \mbox{V}_p = 44 \mbox{ dBmV}; \\ \mbox{f}_q = 805.25 \mbox{ MHz}; \mbox{V}_q = 44 \mbox{ dBmV}; \\ \mbox{measured at } \mbox{f}_p + \mbox{f}_q = 860.5 \mbox{ MHz}. \end{array}$
- 2. Measured according to DIN45004B: $f_p = 851.25 \text{ MHz}; V_p = V_0;$ $f_q = 858.25 \text{ MHz}; V_q = V_o -6 \text{ dB};$ $f_r = 860.25 \text{ MHz}; V_r = V_o -6 \text{ dB};$ measured at $f_p + f_q - f_r = 849.25 \text{ MHz}.$
- 3. The module normally operates at V_B = 24 V, but is able to withstand supply transients up to 30 V.

BGY887B

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
G _p	power gain	f = 50 MHz	28.5	29.5	dB
		f = 750 MHz	29	-	dB
SL	slope cable equivalent	f = 40 to 750 MHz	0.2	2.2	dB
FL	flatness of frequency response	f = 40 to 750 MHz	-	±0.45	dB
S ₁₁	input return losses	f = 40 to 80 MHz	20	-	dB
		f = 80 to 160 MHz	18.5	-	dB
		f = 160 to 320 MHz	17	-	dB
		f = 320 to 640 MHz	15.5	-	dB
		f = 640 to 750 MHz	14	-	dB
S ₂₂	output return losses	f = 40 to 80 MHz	20	-	dB
		f = 80 to 160 MHz	18.5	_	dB
		f = 160 to 320 MHz	17	-	dB
		f = 320 to 640 MHz	15.5	-	dB
		f = 640 to 750 MHz	14	-	dB
СТВ	composite triple beat	110 channels flat; $V_o = 44 \text{ dBmV};$ measured at 745.25 MHz	-	-50	dB
X _{mod}	cross modulation	110 channels flat; $V_o = 44 \text{ dBmV};$ measured at 55.25 MHz	-	-54	dB
CSO	composite second order distortion	110 channels flat; $V_o = 44 \text{ dBmV};$ measured at 746.5 MHz	-	-56	dB
d ₂	second order distortion	note 1	-	-70	dB
Vo	output voltage	$d_{im} = -60 \text{ dB}; \text{ note } 2$	59	-	dBmV
F	noise figure	see Table 1	_	-	dB
I _{tot}	total current consumption (DC)	note 3	-	340	mA

Table 3 Bandwidth 40 to 750 MHz; V_B = 24 V; T_{mb} = 30 °C; Z_S = Z_L = 75 Ω

- $\begin{array}{ll} 1. & f_p = 55.25 \; \text{MHz}; \; V_p = 44 \; \text{dBmV}; \\ f_q = 691.25 \; \text{MHz}; \; V_q = 44 \; \text{dBmV}; \\ & \text{measured at} \; f_p + f_q = 746.5 \; \text{MHz}. \end{array}$
- 2. Measured according to DIN45004B: $f_p = 740.25 \text{ MHz}; V_p = V_0;$ $f_q = 747.25 \text{ MHz}; V_q = V_o -6 \text{ dB};$ $f_r = 749.25 \text{ MHz}; V_r = V_o -6 \text{ dB};$ measured at $f_p + f_q - f_r = 738.25 \text{ MHz}.$
- 3. The module normally operates at $V_B = 24$ V, but is able to withstand supply transients up to 30 V.

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SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
G _p	power gain	f = 50 MHz	28.5	29.5	dB
		f = 600 MHz	29	-	dB
SL	slope cable equivalent	f = 40 to 600 MHz	_	2	dB
FL	flatness of frequency response	f = 40 to 600 MHz	-	±0.35	dB
S ₁₁	input return losses	f = 40 to 80 MHz	20	-	dB
		f = 80 to 160 MHz	18.5	-	dB
		f = 160 to 320 MHz	17	-	dB
		f = 320 to 600 MHz	16	-	dB
S ₂₂	output return losses	f = 40 to 80 MHz	20	-	dB
		f = 80 to 160 MHz	18.5	-	dB
		f = 160 to 320 MHz	17	-	dB
		f = 320 to 600 MHz	16	-	dB
СТВ	composite triple beat	85 channels flat; V _o = 44 dBmV; measured at 595.25 MHz	_	-55	dB
X _{mod}	cross modulation	85 channels flat; $V_o = 44 \text{ dBmV};$ measured at 55.25 MHz	-	-56	dB
CSO	composite second order distortion $V_0 = 44 \text{ dBmV};$ measured at 596		-	-60	dB
d ₂	second order distortion	note 1	-	-72	dB
Vo	output voltage	d _{im} = -60 dB; note 2	61	-	dBmV
F	noise figure	see Table 1	-	-	dB
I _{tot}	total current consumption (DC)	note 3	_	340	mA

Table 4 Bandwidth 40 to 600 MHz; $V_B = 24$ V; $T_{mb} = 30$ °C; $Z_S = Z_L = 75$ Ω

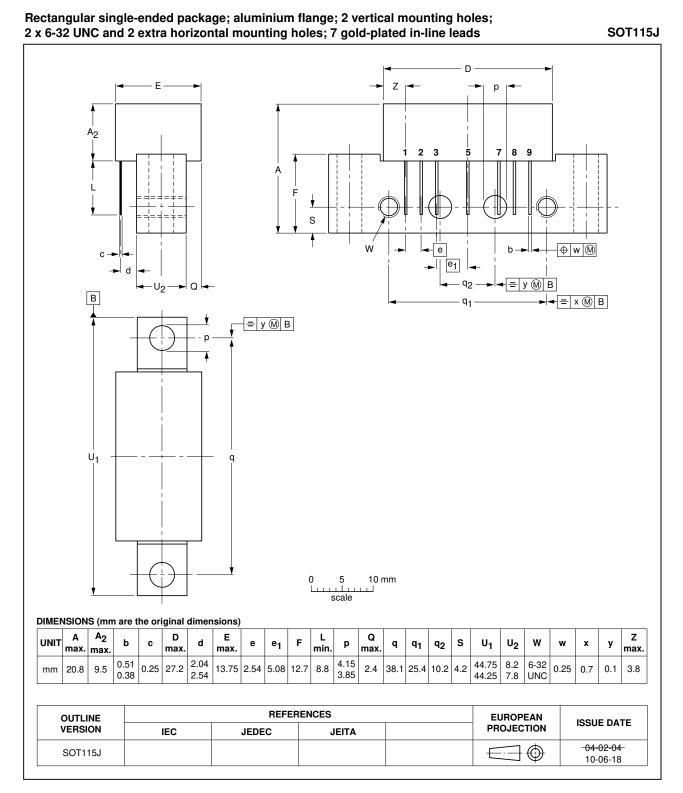
- $\begin{array}{ll} 1. & f_p = 55.25 \mbox{ MHz}; \mbox{ } V_p = 44 \mbox{ dBmV}; \\ f_q = 541.25 \mbox{ MHz}; \mbox{ } V_q = 44 \mbox{ dBmV}; \\ measured \mbox{ at } f_p + f_q = 596.5 \mbox{ MHz}. \end{array}$
- 2. Measured according to DIN45004B: $f_p = 590.25 \text{ MHz}; V_p = V_0;$ $f_q = 597.25 \text{ MHz}; V_q = V_o -6 \text{ dB};$ $f_r = 599.25 \text{ MHz}; V_r = V_o -6 \text{ dB};$ measured at $f_p + f_q - f_r = 588.25 \text{ MHz}.$
- 3. The module normally operates at V_B = 24 V, but is able to withstand supply transients up to 30 V.

Product specification

CATV amplifier module

BGY887B

PACKAGE OUTLINE



BGY887B

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

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